



Materials Declaration Form


IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	13-11-2019
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
	Legal Declaration *
	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F301K6T7	S35V*439XXXZ	A	998Z	13-11-2019
	Amount	UoM	Unit type	ST ECOPACK Grade
	183.63	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7X1.4	32	L Bend	
Comment	Package : 5V LQFP 32 7x7x1.4 1 0060661			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-16th July 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	S35V*439XXZ			6000001.0	1000003.8	
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	9.764	mg	supplier	die	Silicon (Si)	7440-21-3		9.348	mg	957395	50907
				supplier	metallization	Aluminium (Al)	7429-90-5		0.028	mg	2868	152
				supplier	metallization	Copper (Cu)	7440-50-8		0.141	mg	14441	768
				supplier	metallization	Cobalt (Co)	7440-48-4		0.026	mg	2663	142
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	819	44
				supplier	metallization	Tungsten (W)	7440-33-7		0.015	mg	1536	82
				supplier	Passivation	Silicon Nitride	12033-89-5		0.019	mg	1946	103
				supplier	Passivation	Silicon Oxide	7631-86-9		0.179	mg	18333	975
Glue Epoxy_3230_Henkel	M-011 Other inorganic materials	1.307	mg	Supplier	Metals	Silver	7440-22-4		1.066	mg	815000	5803
				Supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))	39817-09-9		0.039	mg	30000	214
				Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.039	mg	30000	214
				Supplier	Organic Compounds	Epoxy resin	Unknown		0.039	mg	30000	214
				Supplier	Organic Compounds	Dodecyclohexane	3234-28-4		0.039	mg	30000	214
				Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.039	mg	30000	214
				Supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.039	mg	30000	214
				Supplier	Metallic compounds	Copper oxide	1317-38-0		0.007	mg	5000	36
Encapsulation_EME-G631SHQ_Sumit	M-011 Other inorganic materials	115.606	mg	Supplier	Plastics/polymers	Epoxy Resin A	Trade Secret		2.428	mg	21000	13221
				Supplier	Plastics/polymers	Epoxy Resin B	Trade Secret		2.428	mg	21000	13221
				Supplier	Plastics/polymers	Phenol Resin	Trade Secret		6.474	mg	56000	35256
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		90.225	mg	780450	491348
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		13.332	mg	115320	72602
				Supplier	Non-metals	Carbon Black	1333-86-4		0.720	mg	6230	3922
Wire_AG Si TYPE_MKE	Bonding Wire	0.225	mg	Supplier	Metals	Silver	7440-22-4		0.216	mg	960000	1174
				Supplier	Metals	Gold	7440-57-5		0.001	mg	5000	6
				Supplier	Metals	Palladium	7440-05-3		0.007	mg	30000	37
				Supplier	Metals	Platinum	7440-06-4		0.001	mg	5000	6
Plating anode_Pure Tin_ASAHI	M-011 Other inorganic materials	0.719	mg	Supplier	Metals	Tin	7440-31-5		0.719	mg	1000000	3915
Leadframe_C9+Ag_HDS	Copper & its alloys	56.007	mg	Supplier	Metals	Copper	7440-50-8		51.366	mg	917140	279731
				Supplier	Metals	Iron	7439-89-6		1.176	mg	21000	6405
				Supplier	Metals	Zinc	7440-66-6		0.064	mg	1150	351
				Supplier	Non-metals	Phosphorus	7723-14-0		0.064	mg	1150	351
				Supplier	Metals	Silver	7440-22-4		3.332	mg	59500	18148
				JIG-R	Metals	Lead	7439-92-1		0.003	mg	60	18